

Vishay Siliconix

N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)			
20	0.008 @ V _{GS} = 10 V	17			
	0.012 @ $V_{GS} = 4.5 V$	14			



Bottom View
Ordering Information: Si7344DP-T1

Si7344DP-T1—E3 (Lead (Pb)-Free)

FEATURES

- TrenchFET[®] Power MOSFET
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07-mm Profile
- PWM Optimized

APPLICATIONS

- DC/DC conversion High-Side
 - Desktop
 - Server
- Synchronous Rectification



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise n	oted		
Parameter		Symbol	10 secs	Steady State	Unit
Drain-Source Voltage		V _{DS}	20		V
Gate-Source Voltage		V _{GS}	±20		
Continuous Drain Current (T 150°C)a	T _A = 25°C	- I _D	17	11	٨
Continuous Drain Current (T _J = 150°C) ^a	T _A = 70°C		14	9	
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	50		A
Continuous Source Current (Diode Conduction) ^a		۱ _S	3.7	1.6	
	T _A = 25°C	P _D	4.1	1.8	W
Maximum Power Dissipation ^a	$T_A = 70^{\circ}C$		2.6	1.1	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{b,c}			260		

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Movinum lunction to Ambienta	$t \le 10 \text{ sec}$	R _{thJA}	22	30	°C/W
Maximum Junction-to-Ambient ^a	Steady State		55	70	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	4.5	5.5	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

* Pb containing terminations are not RoHS compliant, exemptions may apply.



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SPECIFICATIONS $T_J = 25$	°C, unless	otherwise noted					
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.8		2.1	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS} –	$V_{DS} = 20 V, V_{GS} = 0 V$			1		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30			А	
Drain-Source On-State Resistance ^a	-	V _{GS} = 10 V, I _D = 17 A		0.006			
	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 14 \text{ A}$		0.0095	0.012	Ω	
Forward Transconductance ^a	g _{fs}	$V_{DS} = 6 V, I_{D} = 17 A$		33		S	
Diode Forward Voltage ^a	V _{SD}	$I_{S} = 3.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.75	1.1	V	
Dynamic ^b	1 1						
Total Gate Charge	Qg			10	15	nC	
Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 17 A		3.3			
Gate-Drain Charge	Q _{gd}			3.1			
Gate Resistance	Rg			1.0		Ω	
Turn-On Delay Time	t _{d(on)}			14	25		
Rise Time	t _r	V_{DD} = 10 V, R_L = 10 Ω		15	25		
Turn-Off Delay Time	$t_{d(off)}$ $I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_G = 6 \Omega$	$\text{I}_\text{D}\cong \text{1}$ A, V_GEN = 10 V, R_G = 6 Ω		40	65	ns	
Fall Time	t _f			15	25		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3.7 A, di/dt = 100 A/μs		35	70		

Notes a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C unless noted







Source-Drain Diode Forward Voltage

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Si7344DP

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TYPICAL CHARACTERISTICS 25 °C unless noted







Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72128.

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